

REMARKS

Applicants respectfully request consideration of the subject application as amended herein. This Amendment is submitted in response to the Final Office Action mailed October 5, 2006. Claims 1-44 stand rejected. In this Amendment, claims 1, 3, 19, 29 and 36 have been amended. No new matter has been added.

35 U.S.C. §102

The Examiner rejected claims 1-44 under 35 U.S.C. §102(e) as being anticipated by Redeker, et al., (U.S. Patent No. 6,869,332, hereinafter “Redeker”). As discussed below, the pending claims are patentable over the above reference.

Redeker discloses polishing a substrate using a general purpose computer and a closed-loop feedback system. Redeker is directed to determining whether the polishing process is complete. Redeker refers to a “pressure profile applied by the carrier head” (col. 3, lines 26-27).

Contrary to the presently claimed invention, Redeker does not teach or suggest iteratively adjusting parameters of a process recipe when qualifying polishing and clearing platens of a manufacturing tool, and then using the final recipe in the processing of subsequent wafers by each platen of the manufacturing tool. These limitations are also missing from the U.S. Patent No. 6,776,692 (“the ‘692 patent”) incorporated into Redeker by reference. In particular, the ‘692 patent at most teaches obtaining thickness-related measurements of a sample wafer, comparing them to the target profile, and making adjustments to the chamber pressures prior to or during polishing of other wafers (‘692 patent, col. 2, lines 39-44). Hence, similarly to Redekar, the ‘692 patent does not teach or suggest iteratively adjusting parameters of the process recipe when qualifying polishing and clearing platens of a manufacturing tool, and then using the final recipe in the processing of subsequent wafers by each platen of the manufacturing tool.

The above limitations of the presently claimed invention are included in the following language of claim 3:

... (c) after measuring qualification characteristics of one of the set of platens, qualifying the one of the set of platens of said manufacturing tool by adjusting one or more parameters of a process recipe in accordance with said one or more qualification characteristics measured from said wafer to target one or more specifications of the one of the set of platens;

(d) repeating the adjustment of parameters of the recipe while qualifying each other of the set of platens, to provide a final recipe; and

(e) using said final recipe in the processing of one or more subsequent wafers by each of the set of platens of said manufacturing tool.

Similar language is also included in independent claims 1, 19, 29 and 36. Accordingly, the present invention as claimed in claims 1, 3, 19, 29 and 26 and their corresponding dependent claims is not anticipated by Redekar. Applicant respectfully requests the withdrawal of the rejection under 35 U.S.C. §102(e) and submits that the pending claims are in condition for allowance.

DEPOSIT ACCOUNT AUTHORIZATION


Authorization is hereby given to charge our Deposit Account No. 02-2666 for any charges that may be due. Furthermore, if an extension is required, then Applicant hereby requests such extension.

If the Examiner determines the prompt allowance of these claims could be facilitated by a telephone conference, the Examiner is invited to contact Marina Portnova at (408) 720-8300.

Respectfully submitted,

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